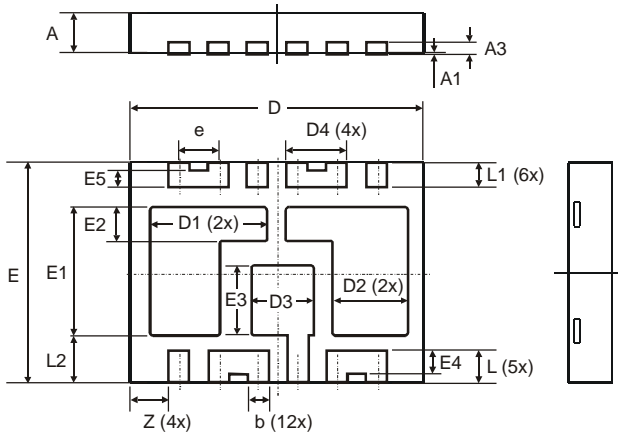


Package Outline Dimensions

U-DFN4030-12 (Type B)

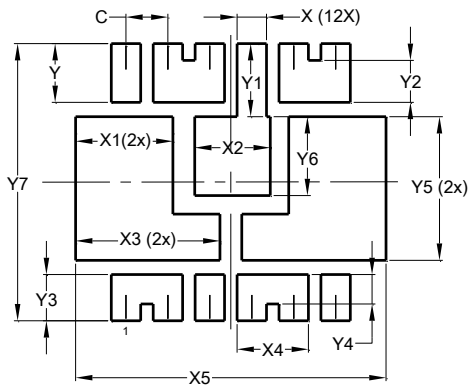


U-DFN4030-12 Type B							
Dim	Min	Max	Typ	Dim	Min	Max	Typ
A	0.55	0.65	0.60	e	-	-	0.50
A1	0.00	0.05	0.02	E1	1.51	1.71	1.61
A3	-	-	0.15	E2	0.35	0.55	0.45
B	0.20	0.30	0.25	E3	0.74	0.94	0.84
D	3.95	4.05	4.00	E4	0.30	0.50	0.40
D1	1.52	1.72	1.62	E5	0.15	0.35	0.25
D2	0.96	1.16	1.06	L	0.45	0.55	0.50
D3	0.70	0.90	0.80	L1	0.30	0.40	0.35
D4	0.65	0.85	0.75	L2	0.72	0.82	0.77
E	2.95	3.05	3.00	Z	-	-	0.625

All Dimensions in mm

Suggested Pad Layout

U-DFN4030-12 (Type B)



Dimensions	Value (in mm)
C	0.500
X	0.350
X1	1.160
X2	0.900
X3	1.720
X4	0.850
X5	3.700
Y	0.700
Y1	0.870
Y2	0.500
Y3	0.550
Y4	0.350
Y5	1.710
Y6	0.940
Y7	3.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.